

Title (en)

Process for making ceramic insulated supports by piling up layers.

Title (de)

Verfahren zum Herstellen von keramischen Durchführungsisolatoren durch den Aufbau von mehreren Schichten.

Title (fr)

Procédé d'obtention d'inserts céramiques isolants par empilement multicouches.

Publication

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Application

EP 93420119 A 19930316

Priority

FR 9204257 A 19920323

Abstract (en)

[origin: US5346749A] A process for manufacturing insulating ceramic inserts used as sealed passages for electrical conductors through a metallic wall, is described wherein a green ceramic plate is subjected to silk-screen printing with the aid of a conducting ink, generally in ring-shaped patterns. The patterns are pressed and holes are pierced through the center of the ring and through at least one other green plate. The silk-screen printed plate is pressed against the at least one other green plate, or between two other green plates, bringing the holes into coincidence. A cut-out is made around each of the holes and the outer lateral surface of the part obtained is metallized. The part is then heat treated in order to fire and sinter same. It also is possible for the sintering to be performed before the metallization of the outer lateral surface.

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